Renesas Electronics America Inc - R5F2L3AACDFA#U0 Datasheet

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	LCD, POR, PWM, Voltage Detect, WDT
Number of I/O	88
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 20x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-BQFP
Supplier Device Package	100-QFP (14x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2l3aacdfa-u0

Table 1.2 Programmable I/O Ports Provided for Each Group

Programmable I/O Port	R8C/L35C Group Total: 41 I/O pins								R8C/L36C Group Total: 52 I/O pins								R8C/L38C Group Total: 68 I/O pins								R8C/L3AC Group Total: 88 I/O pins							
	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
P0	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P1	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P2	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P3	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P4	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P5	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	✓	✓	✓	✓
P6	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P7	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P10	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓
P11	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P12	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓
P13	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓

Notes:
1. The symbol "✓" indicates a programmable I/O port.
2. The symbol "–" indicates the settings should be made as follows:
   - Set 1 to the corresponding bits in the PDi (i = 1 to 3, 5 to 7, and 10 to 13) register.
   - Set 0 to the corresponding bits in the Pi (i = 1 to 3, 5 to 7, and 10 to 13) register.
   - Set 0 to the corresponding bits in the P10DRR or P11DRR register.

Table 1.3 LCD Display Function Pins Provided for Each Group

Shared I/O Port	L35C Group Common output: Max. 4 Segment output: Max. 24								L36C Group Common output: Max. 8 Segment output: Max. 32								L38C Group Common output: Max. 8 Segment output: Max. 48								L3AC Group Common output: Max. 8 Segment output: Max. 56							
P0	SEG 7	SEG 6	SEG 5	SEG 4	SEG 3	SEG 2	SEG 1	SEG 0	SEG 7	SEG 6	SEG 5	SEG 4	SEG 3	SEG 2	SEG 1	SEG 0	SEG 7	SEG 6	SEG 5	SEG 4	SEG 3	SEG 2	SEG 1	SEG 0	SEG 7	SEG 6	SEG 5	SEG 4	SEG 3	SEG 2	SEG 1	SEG 0
P1	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	SEG 11	SEG 10	SEG 9	SEG 8	SEG 15	SEG 14	SEG 13	SEG 12	SEG 11	SEG 10	SEG 9	SEG 8
P2	SEG 23	SEG 22	SEG 21	SEG 20	–	–	–	–	SEG 23	SEG 22	SEG 21	SEG 20	–	–	–	–	SEG 23	SEG 22	SEG 21	SEG 20	SEG 19	SEG 18	SEG 17	SEG 16	SEG 23	SEG 22	SEG 21	SEG 20	SEG 19	SEG 18	SEG 17	SEG 16
P3	–	–	–	–	SEG 27	SEG 26	SEG 25	SEG 24	SEG 31	SEG 30	SEG 29	SEG 28	SEG 27	SEG 26	SEG 25	SEG 24	SEG 31	SEG 30	SEG 29	SEG 28	SEG 27	SEG 26	SEG 25	SEG 24	SEG 31	SEG 30	SEG 29	SEG 28	SEG 27	SEG 26	SEG 25	SEG 24
P4	SEG 39	SEG 38	SEG 37	SEG 36	SEG 35	SEG 34	SEG 33	SEG 32	SEG 39	SEG 38	SEG 37	SEG 36	SEG 35	SEG 34	SEG 33	SEG 32	SEG 39	SEG 38	SEG 37	SEG 36	SEG 35	SEG 34	SEG 33	SEG 32	SEG 39	SEG 38	SEG 37	SEG 36	SEG 35	SEG 34	SEG 33	SEG 32
P5	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	SEG 43	SEG 42	SEG 41	SEG 40
P6	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	SEG 51	SEG 50	SEG 49	SEG 48	SEG 47	SEG 46	SEG 45	SEG 44	SEG 51	SEG 50	SEG 49	SEG 48	SEG 47	SEG 46	SEG 45	SEG 44
P7	COM 0	COM 1	COM 2	COM 3	–	–	–	–	COM 0	COM 1	COM 2	COM 3	SEG 55	SEG 54	SEG 53	SEG 52	COM 0	COM 1	COM 2	COM 3	SEG 55	SEG 54	SEG 53	SEG 52	COM 0	COM 1	COM 2	COM 3	SEG 55	SEG 54	SEG 53	SEG 52
P12	–	–	–	–	CL2	CL1	–	–	–	–	–	–	CL2	CL1	–	–	–	–	–	–	CL2	CL1	–	–	–	–	–	–	CL2	CL1	–	–
–	VL1								VL1								VL1								VL1							
–	VL2								VL2								VL2								VL2							
–	–								VL3								VL3								VL3							
–	VL4								VL4								VL4								VL4							

Notes:
1. The symbol "–" indicates there is no LCD display function. Set the corresponding bits in registers LSE1 to LSE3, LSE5 to LSE7 to 0 for these pins.
2. SEG52 to SEG55 can be used as COM7 to COM4.
   The R8C/L35C Group does not have pins SEG52 to SEG55, so 1/8 duty cannot be selected.
3. The R8C/L35C Group does not have the VL3 pin, so 1/4 bias cannot be selected. When the internal voltage multiplier is used, 1/2 bias cannot also be selected.

1.1.3 Specifications

Tables 1.4 to 1.6 list the Specifications.

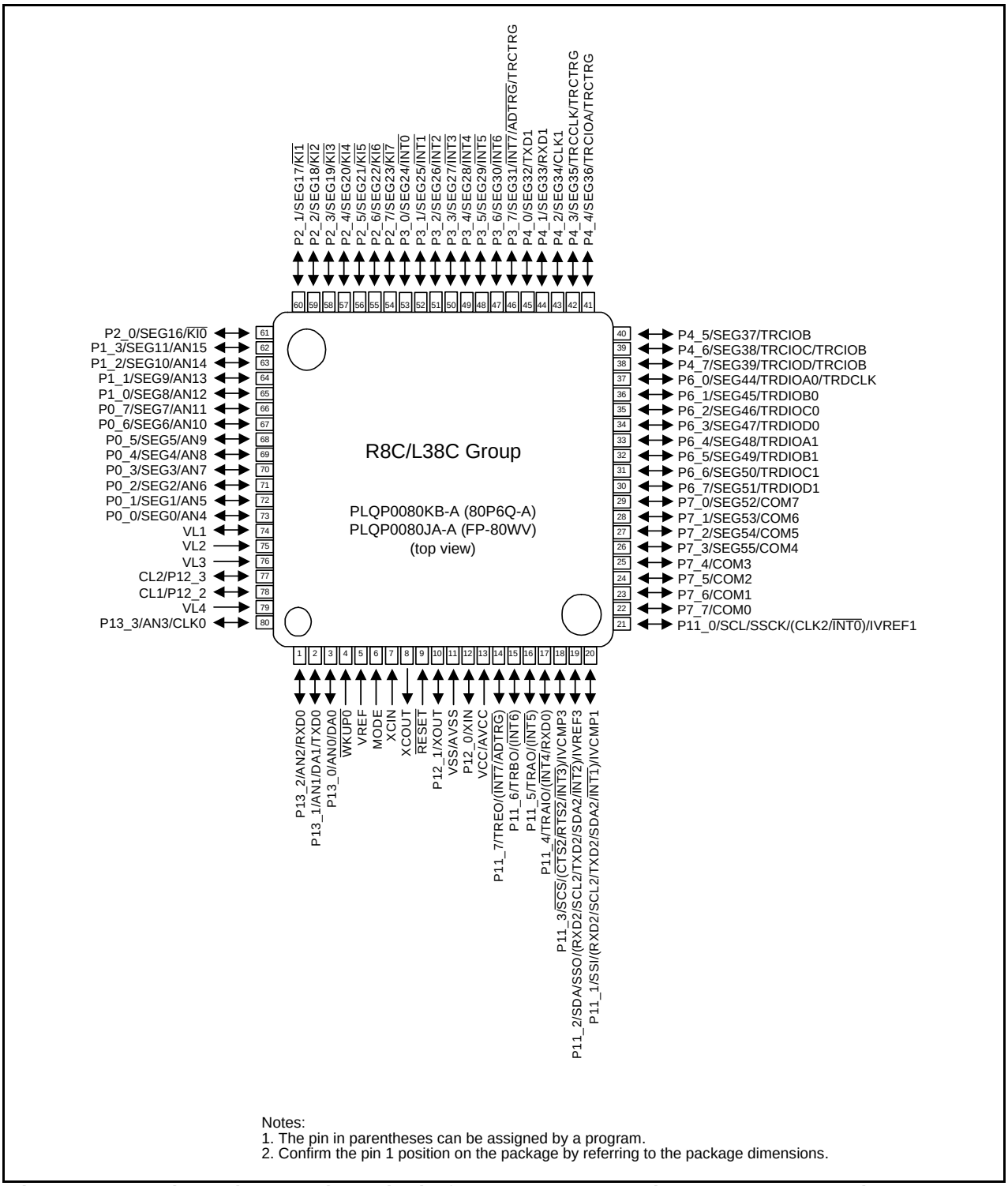
Table 1.4 Specifications (1)

Item	Function		Specification
CPU	Central processing unit		R8C CPU core • Number of fundamental instructions: 89 • Minimum instruction execution time: 50 ns (f(XIN) = 20 MHz, VCC = 2.7 to 5.5 V) 200 ns (f(XIN) = 5 MHz, VCC = 1.8 to 5.5 V) • Multiplier: 16 bits × 16 bits → 32 bits • Multiply-accumulate instruction: 16 bits × 16 bits + 32 bits → 32 bits • Operating mode: Single-chip mode (address space: 1 Mbyte)
Memory	ROM/RAM Data flash		Refer to **Tables 1.7 to 1.10 Product Lists**.
Power Supply Voltage Detection	Voltage detection circuit		• Power-on reset • Voltage detection 3 (detection level of voltage detection 0 and voltage detection 1 selectable)
I/O Ports	Programmable I/O ports	R8C/L35C Group	• CMOS I/O ports: 41, selectable pull-up resistor • High current drive ports: 5
		R8C/L36C Group	• CMOS I/O ports: 52, selectable pull-up resistor • High current drive ports: 8
		R8C/L38C Group	• CMOS I/O ports: 68, selectable pull-up resistor • High current drive ports: 8
		R8C/L3AC Group	• CMOS I/O ports: 88, selectable pull-up resistor • High current drive ports: 16
Clock	Clock generation circuits		4 circuits: XIN clock oscillation circuit XCIN clock oscillation circuit (32 kHz) High-speed on-chip oscillator (with frequency adjustment function) Low-speed on-chip oscillator • Oscillation stop detection: XIN clock oscillation stop detection function • Frequency divider circuit: Division ratio selectable from 1, 2, 4, 8, and 16 • Low-power-consumption modes: Standard operating mode (high-speed clock, low-speed clock, high-speed on-chip oscillator, low-speed on-chip oscillator), wait mode, stop mode, power-off mode
			Real-time clock (timer RE)
Interrupts		R8C/L35C Group	• Number of interrupt vectors: 69 • External Interrupt: 9 ($\overline{\text{INT}}$ × 5, key input × 4) • Priority levels: 7 levels
		R8C/L36C Group	• Number of interrupt vectors: 69 • External Interrupt: 12 ($\overline{\text{INT}}$ × 8, key input × 4) • Priority levels: 7 levels
		R8C/L38C Group	• Number of interrupt vectors: 69 • External Interrupt: 16 ($\overline{\text{INT}}$ × 8, key input × 8) • Priority levels: 7 levels
		R8C/L3AC Group	• Number of interrupt vectors: 69 • External Interrupt: 16 ($\overline{\text{INT}}$ × 8, key input × 8) • Priority levels: 7 levels
Watchdog Timer			• 14 bits × 1 (with prescaler) • Selectable reset start function • Selectable low-speed on-chip oscillator for watchdog timer
DTC (Data Transfer Controller)			• 1 channel • Activation sources: 38 • Transfer modes: 2 (normal mode, repeat mode)

Table 1.6 Specifications (3)

Item	Specification
Flash Memory	• Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance: 10,000 times (data flash) 1,000 times (program ROM) • Program security: ROM code protect, ID code check • On-chip debug function • On-board flash rewrite function • Background operation (BGO) function
Operating Frequency/ Supply Voltage	f(XIN) = 20 MHz (VCC = 2.7 to 5.5 V) f(XIN) = 5 MHz (VCC = 1.8 to 5.5 V)
Current Consumption	Typ. 7 mA (VCC = 5.0 V, f(XIN) = 20 MHz) Typ. 3.6 mA (VCC = 3.0 V, f(XIN) = 10 MHz) Typ. 3.5 μA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) Typ. 2 μA (VCC = 3.0 V, stop mode) Typ. 0.02 μA (VCC = 3.0 V, power-off mode)
Operating Ambient Temperature	-20 to 85°C (N version) -40 to 85°C (D version) (1)

Note:
1. Specify the D version if D version functions are to be used.



Notes:
1. The pin in parentheses can be assigned by a program.
2. Confirm the pin 1 position on the package by referring to the package dimensions.

Figure 1.11 Pin Assignment (Top View) of PLQP0080KB-A and PLQP0080JA-A Packages

Table 1.13 Pin Name Information by Pin Number (3)

Pin Number				Control Pin	Port	I/O Pin Functions for Peripheral Modules						
L3AC (Note 2)	L38C	L36C	L35C			Interrupt	Timer	Serial Interface	SSU	I²C bus	A/D Converter, D/A Converter, Comparator B	LCD drive control circuit
85 [87]	68	49	40		P0_5						AN9	SEG5
86 [88]	69	50	41		P0_4						AN8	SEG4
87 [89]	70	51	42		P0_3						AN7	SEG3
88 [90]	71	52	43		P0_2						AN6	SEG2
89 [91]	72	53	44		P0_1						AN5	SEG1
90 [92]	73	54	45		P0_0						AN4	SEG0
91 [93]	74	55	46									VL1
92 [94]	75	56	47									VL2
93 [95]	76	57										VL3
94 [96]	77	58	48		P12_3							CL2
95 [97]	78	59	49		P12_2							CL1
96 [98]	79	60	50									VL4
97 [99]					P13_7		TRGCLKB				AN19	
98 [100]					P13_6		TRGIOB				AN18	
99 [1]					P13_5		TRGCLKA				AN17	
100 [2]					P13_4		TRGIOA				AN16	

Notes:
1. The pin in parentheses can be assigned by a program.
2. The number in brackets indicates the pin number for the 100P6F package.

1.5 Pin Functions

Tables 1.14 and 1.15 list Pin Functions for R8C/L3AC Group.

Table 1.14 Pin Functions for R8C/L3AC Group (1)

Item	Pin Name	I/O Type	Description
Power supply input	VCC, VSS	–	Apply 1.8 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	–	Power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset input	$\overline{\text{RESET}}$	I	Driving this pin low resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
Power-off mode exit input	$\overline{\text{WKUP0}}$	I	This pin is provided for input to exit the mode used in power-off mode. Connect to VSS when not using power-off mode.
XIN clock input	XIN	I	These pins are provided for XIN clock generation circuit I/O. Connect a ceramic oscillator or a crystal oscillator between pins XIN and XOUT. (1) To use an external clock, input it to the XIN pin and leave the XOUT pin open.
XIN clock output	XOUT	O	
XCIN clock input	XCIN	I	These pins are provided for XCIN clock generation circuit I/O. Connect a crystal oscillator between pins XCIN and XCOUT. (1) To use an external clock, input it to the XCIN pin and leave the XCOUT pin open.
XCIN clock output	XCOUT	O	
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT0}}$ to $\overline{\text{INT7}}$	I	$\overline{\text{INT}}$ interrupt input pins.
Key input interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI7}}$	I	Key input interrupt input pins
Timer RA	TRAIO	I/O	Timer RA I/O pin
	TRAO	O	Timer RA output pin
Timer RB	TRBO	O	Timer RB output pin
Timer RC	TRCCLK	I	External clock input pin
	TRCTRG	I	External trigger input pin
	TRCIOA, TRCIOB, TRCIOC, TRCIOD	I/O	Timer RC I/O pins
Timer RD	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDIOC0, TRDIOC1, TRDIOD0, TRDIOD1	I/O	Timer RD I/O pins
	TRDCLK	I	External clock input pin
Timer RE	TREO	O	Divided clock output pin
Timer RG	TRGCLKA, TRGCLKB	I	Timer RG input pins
	TRGIOA, TRGIOB	I/O	Timer RG I/O pins
Serial interface	CLK0, CLK1, CLK2	I/O	Transfer clock I/O pins
	RXD0, RXD1, RXD2	I	Serial data input pins
	TXD0, TXD1, TXD2	O	Serial data output pins
	$\overline{\text{CTS2}}$	I	Transmission control input pin
	$\overline{\text{RTS2}}$	O	Reception control output pin
	SCL2	I/O	I^2C mode clock I/O pin
	SDA2	I/O	I^2C mode data I/O pin

I: Input O: Output I/O: Input and output

Note:

1. Contact the oscillator manufacturer for oscillation characteristics.

Table 1.15 Pin Functions for R8C/L3AC Group (2)

Item	Pin Name	I/O Type	Description
I^2C bus	SCL	I/O	Clock I/O pin
	SDA	I/O	Data I/O pin
SSU	SSI	I/O	Data I/O pin
	$\overline{SCS}$	I/O	Chip-select signal I/O pin
	SSCK	I/O	Clock I/O pin
	SSO	I/O	Data I/O pin
Reference voltage input	VREF	I	Reference voltage input pin for the A/D converter and the D/A converter
A/D converter	AN0 to AN11	I	A/D converter analog input pins
	$\overline{ADTRG}$	I	A/D external trigger input pin
D/A converter	DA0, DA1	O	D/A converter output pins
Comparator B	IVCMP1, IVCMP3	I	Comparator B analog voltage input pins
	IVREF1, IVREF3	I	Comparator B reference voltage input pins
I/O ports	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0, P5_3, P6_0 to P6_7 P7_0 to P7_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_3, P13_0 to P13_7	I/O	CMOS I/O ports. Each port has an I/O select direction register, allowing each pin in the port to be directed for input or output individually. Any port set to input can be set to use a pull-up resistor or not by a program. Ports P10_0 to P10_7 and P11_0 to P11_7 can be used as LED drive ports.
Segment output	SEG0 to SEG55	O	LCD segment output pins
Common output	COM0 to COM7	O	LCD common output pins
Voltage multiplier capacity connect pins	CL1, CL2	O	Connect pins for the LCD control voltage multiplier
LCD power supply	VL1	I/O	Apply the voltage: $0 \leq VL1 \leq VL2 \leq VL3 \leq VL4$. VL1 can be used as the reference potential input or output pin when setting the voltage multiplier.
	VL2 to VL4	I	

I: Input O: Output I/O: Input and output

Note:

1. Contact the oscillator manufacturer for oscillation characteristics.

Table 4.8 SFR Information (8) (1)

Address	Register	Symbol	After Reset
01C0h	Address Match Interrupt Register 0	RMAD0	XXh
01C1h			XXh
01C2h			0000XXXXb
01C3h	Address Match Interrupt Enable Register 0	AIER0	00h
01C4h	Address Match Interrupt Register 1	RMAD1	XXh
01C5h			XXh
01C6h			0000XXXXb
01C7h	Address Match Interrupt Enable Register 1	AIER1	00h
01C8h			
01C9h			
01CAh			
01CBh			
01CCh			
01CDh			
01CEh			
01CFh			
01D0h			
01D1h			
01D2h			
01D3h			
01D4h			
01D5h			
01D6h			
01D7h			
01D8h			
01D9h			
01DAh			
01DBh			
01DCh			
01DDh			
01DEh			
01DFh			
01E0h	Port P0 Pull-Up Control Register	P0PUR	00h
01E1h	Port P1 Pull-Up Control Register	P1PUR	00h
01E2h	Port P2 Pull-Up Control Register	P2PUR	00h
01E3h	Port P3 Pull-Up Control Register	P3PUR	00h
01E4h	Port P4 Pull-Up Control Register	P4PUR	00h
01E5h	Port P5 Pull-Up Control Register	P5PUR	00h
01E6h	Port P6 Pull-Up Control Register	P6PUR	00h
01E7h	Port P7 Pull-Up Control Register	P7PUR	00h
01E8h			
01E9h			
01EAh	Port 10 Pull-Up Control Register	P10PUR	00h
01EBh	Port 11 Pull-Up Control Register	P11PUR	00h
01ECh	Port 12 Pull-Up Control Register	P12PUR	00h
01EDh	Port 13 Pull-Up Control Register	P13PUR	00h
01EEh			
01EFh			
01F0h	Port P10 Drive Capacity Control Register	P10DRR	00h
01F1h	Port P11 Drive Capacity Control Register	P11DRR	00h
01F2h			
01F3h			
01F4h			
01F5h	Input Threshold Control Register 0	VLT0	00h
01F6h	Input Threshold Control Register 1	VLT1	00h
01F7h	Input Threshold Control Register 2	VLT2	00h
01F8h	Comparator B Control Register 0	INTCMP	00h
01F9h			
01FAh	External Input Enable Register 0	INTEN	00h
01FBh	External Input Enable Register 1	INTEN1	00h
01FCh	INT Input Filter Select Register 0	INTF	00h
01FDh	INT Input Filter Select Register 1	INTF1	00h
01FEh	Key Input Enable Register 0	KIEN	00h
01FFh	Key Input Enable Register 1	KIEN1	00h

X: Undefined

Note:

1. Blank spaces are reserved. No access is allowed.

Table 4.9 SFR Information (9) (1)

Address	Register	Symbol	After Reset
0200h	LCD Control Register	LCR0	00h
0201h	LCD Bias Control Register	LCR1	00h
0202h	LCD Display Control Register	LCR2	X0000000b
0203h	LCD Clock Control Register	LCR3	00h
0204h			
0205h			
0206h	LCD Port Select Register 0	LSE0	00h
0207h	LCD Port Select Register 1	LSE1	00h
0208h	LCD Port Select Register 2	LSE2	00h
0209h	LCD Port Select Register 3	LSE3	00h
020Ah	LCD Port Select Register 4	LSE4	00h
020Bh	LCD Port Select Register 5	LSE5	00h
020Ch	LCD Port Select Register 6	LSE6	00h
020Dh	LCD Port Select Register 7	LSE7	00h
020Eh			
020Fh			
0210h	LCD Display Data Register	LRA0L	XXh
0211h		LRA1L	XXh
0212h		LRA2L	XXh
0213h		LRA3L	XXh
0214h		LRA4L	XXh
0215h		LRA5L	XXh
0216h		LRA6L	XXh
0217h		LRA7L	XXh
0218h		LRA8L	XXh
0219h		LRA9L	XXh
021Ah		LRA10L	XXh
021Bh		LRA11L	XXh
021Ch		LRA12L	XXh
021Dh		LRA13L	XXh
021Eh		LRA14L	XXh
021Fh		LRA15L	XXh
0220h		LRA16L	XXh
0221h		LRA17L	XXh
0222h		LRA18L	XXh
0223h		LRA19L	XXh
0224h		LRA20L	XXh
0225h		LRA21L	XXh
0226h		LRA22L	XXh
0227h		LRA23L	XXh
0228h		LRA24L	XXh
0229h		LRA25L	XXh
022Ah		LRA26L	XXh
022Bh		LRA27L	XXh
022Ch		LRA28L	XXh
022Dh		LRA29L	XXh
022Eh		LRA30L	XXh
022Fh		LRA31L	XXh
0230h		LRA32L	XXh
0231h		LRA33L	XXh
0232h		LRA34L	XXh
0233h		LRA35L	XXh
0234h		LRA36L	XXh
0235h		LRA37L	XXh
0236h		LRA38L	XXh
0237h		LRA39L	XXh
0238h		LRA40L	XXh
0239h		LRA41L	XXh
023Ah		LRA42L	XXh
023Bh		LRA43L	XXh
023Ch		LRA44L	XXh
023Dh		LRA45L	XXh
023Eh		LRA46L	XXh
023Fh		LRA47L	XXh

X: Undefined

Note:

1. Blank spaces are reserved. No access is allowed.

Table 4.10 SFR Information (10) (1)

Address	Register	Symbol	After Reset
0240h	LCD Display Data Register	LRA48L	XXh
0241h		LRA49L	XXh
0242h		LRA50L	XXh
0243h		LRA51L	XXh
0244h		LRA52L	XXh
0245h		LRA53L	XXh
0246h		LRA54L	XXh
0247h		LRA55L	XXh
0248h			
0249h			
024Ah			
024Bh			
024Ch			
024Dh			
024Eh			
024Fh			
0250h			
0251h			
0252h			
0253h			
0254h			
0255h			
0256h			
0257h			
0258h			
0259h			
025Ah			
025Bh			
025Ch			
025Dh			
025Eh			
025Fh			
0260h			
0261h			
0262h			
0263h			
0264h			
0265h			
0266h			
0267h			
0268h			
0269h			
026Ah			
026Bh			
026Ch			
026Dh			
026Eh			
026Fh			
0270h	LCD Display Control Data Register	LRA0H	XXh
0271h		LRA1H	XXh
0272h		LRA2H	XXh
0273h		LRA3H	XXh
0274h		LRA4H	XXh
0275h		LRA5H	XXh
0276h		LRA6H	XXh
0277h		LRA7H	XXh
0278h		LRA8H	XXh
0279h		LRA9H	XXh
027Ah		LRA10H	XXh
027Bh		LRA11H	XXh
027Ch		LRA12H	XXh
027Dh		LRA13H	XXh
027Eh		LRA14H	XXh
027Fh		LRA15H	XXh

X: Undefined

Note:

1. Blank spaces are reserved. No access is allowed.

Table 4.15 SFR Information (15) (1)

Address	Register	Symbol	After Reset
2CB0h	DTC Control Data 14	DTCD14	XXh
2CB1h			XXh
2CB2h			XXh
2CB3h			XXh
2CB4h			XXh
2CB5h			XXh
2CB6h			XXh
2CB7h			XXh
2CB8h	DTC Control Data 15	DTCD15	XXh
2CB9h			XXh
2CBAh			XXh
2CBBh			XXh
2CBCh			XXh
2CBDh			XXh
2CBEh			XXh
2CBFh			XXh
2CC0h	DTC Control Data 16	DTCD16	XXh
2CC1h			XXh
2CC2h			XXh
2CC3h			XXh
2CC4h			XXh
2CC5h			XXh
2CC6h			XXh
2CC7h			XXh
2CC8h	DTC Control Data 17	DTCD17	XXh
2CC9h			XXh
2CCAh			XXh
2CCBh			XXh
2CCCh			XXh
2CCDh			XXh
2CCEh			XXh
2CCFh			XXh
2CD0h	DTC Control Data 18	DTCD18	XXh
2CD1h			XXh
2CD2h			XXh
2CD3h			XXh
2CD4h			XXh
2CD5h			XXh
2CD6h			XXh
2CD7h			XXh
2CD8h	DTC Control Data 19	DTCD19	XXh
2CD9h			XXh
2CDAh			XXh
2CDBh			XXh
2CDCh			XXh
2CDDh			XXh
2CDEh			XXh
2CDFh			XXh
2CE0h	DTC Control Data 20	DTCD20	XXh
2CE1h			XXh
2CE2h			XXh
2CE3h			XXh
2CE4h			XXh
2CE5h			XXh
2CE6h			XXh
2CE7h			XXh
2CE8h	DTC Control Data 21	DTCD21	XXh
2CE9h			XXh
2CEAh			XXh
2CEBh			XXh
2CECh			XXh
2CEDh			XXh
2CEEh			XXh
2CEFh			XXh

X: Undefined
Note:
1. Blank spaces are reserved. No access is allowed.

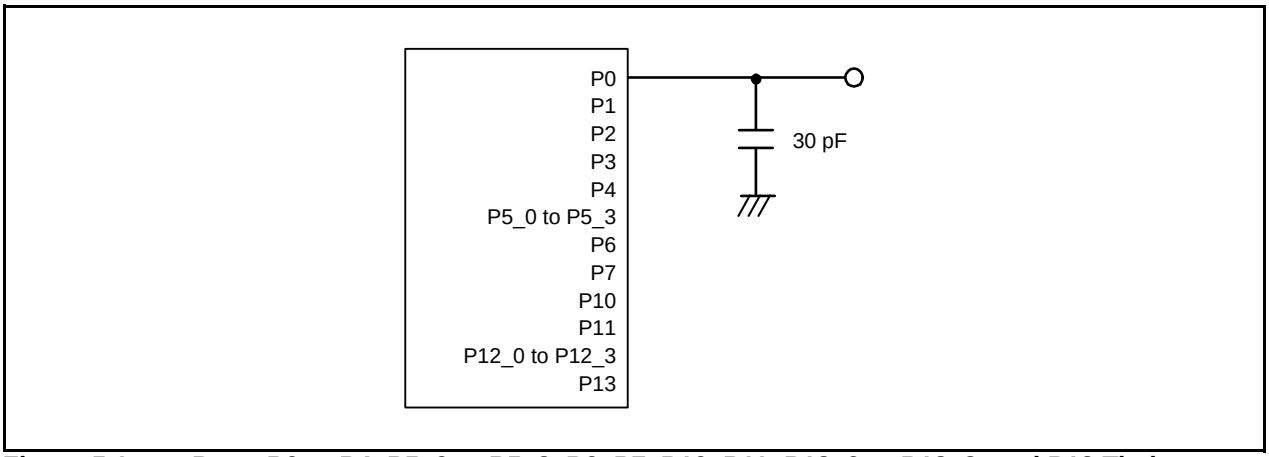


Figure 5.1 Ports P0 to P4, P5_0 to P5_3, P6, P7, P10, P11, P12_0 to P12_3, and P13 Timing Measurement Circuit

Table 5.6 Flash Memory (Program ROM) Characteristics
(V_{CC} = 2.7 to 5.5 V and T_{opr} = 0 to 60°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance (1)		1,000 (2)	—	—	times
—	Byte program time		—	80	500	µs
—	Block erase time		—	0.3	—	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		—	—	5 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	ms
—	Time from suspend until erase restart		—	—	30+CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly terminated until reading is enabled		—	—	30+CPU clock × 1 cycle	µs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		0	—	60	°C
—	Data hold time (6)	Ambient temperature = 55°C	20	—	—	year

Notes:
1. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.7 Flash Memory (Data flash Block A to Block D) Characteristics (V_{CC} = 2.7 to 5.5 V and T_{opr} = −20 to 85°C (N version) / −40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance (1)		10,000 (2)	—	—	times
—	Byte program time (program/erase endurance ≤ 1,000 times)		—	160	1500	µs
—	Byte program time (program/erase endurance > 1,000 times)		—	300	1500	µs
—	Block erase time (program/erase endurance ≤ 1,000 times)		—	0.2	1	s
—	Block erase time (program/erase endurance > 1,000 times)		—	0.3	1	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		—	—	5 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	ms
—	Time from suspend until erase restart		—	—	30+CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly terminated until reading is enabled		—	—	30+CPU clock × 1 cycle	µs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		−20 (6)	—	85	°C
—	Data hold time (7)	Ambient temperature = 55 °C	20	—	—	year

Notes:
1. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. In addition, averaging the erasure endurance between blocks A to D can further reduce the actual erasure endurance. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. −40°C for D version.
7. The data hold time includes time that the power supply is off or the clock is not supplied.

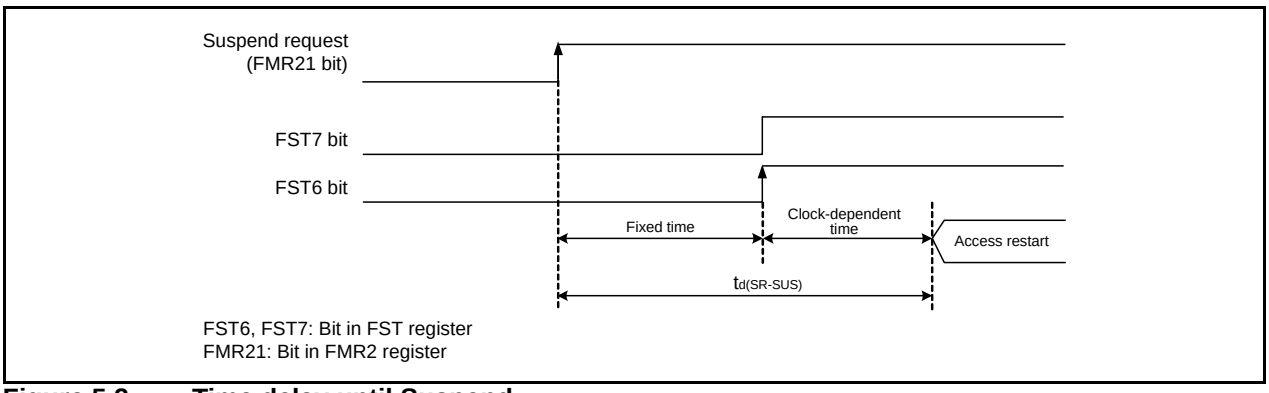


Figure 5.2 Time delay until Suspend

Table 5.8 Voltage Detection 0 Circuit Characteristics (Vcc = 1.8 to 5.5 V and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{det0}	Voltage detection level Vdet0_0 (1)		1.80	1.90	2.05	V
	Voltage detection level Vdet0_1 (1)		2.15	2.35	2.50	V
	Voltage detection level Vdet0_2 (1)		2.70	2.85	3.05	V
	Voltage detection level Vdet0_3 (1)		3.55	3.80	4.05	V
—	Voltage detection 0 circuit response time (3)	At the falling of Vcc from 5 V to (Vdet0_0 – 0.1) V	—	6	150	µs
—	Voltage detection circuit self power consumption	VCA25 = 1, Vcc = 5.0 V	—	1.5	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (2)		—	—	100	µs

Notes:
1. Select the voltage detection level with bits VDSEL0 and VDSEL1 in the OFS register.
2. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA25 bit in the VCA2 register to 0.
3. Time until the voltage monitor 0 reset is generated after the voltage passes V_{det0}.

Table 5.9 Voltage Detection 1 Circuit Characteristics (Vcc = 1.8 to 5.5 V and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{det1}	Voltage detection level Vdet1_0 (1)	At the falling of Vcc	2.00	2.20	2.40	V
	Voltage detection level Vdet1_1 (1)	At the falling of Vcc	2.15	2.35	2.55	V
	Voltage detection level Vdet1_2 (1)	At the falling of Vcc	2.30	2.50	2.70	V
	Voltage detection level Vdet1_3 (1)	At the falling of Vcc	2.45	2.65	2.85	V
	Voltage detection level Vdet1_4 (1)	At the falling of Vcc	2.60	2.80	3.00	V
	Voltage detection level Vdet1_5 (1)	At the falling of Vcc	2.75	2.95	3.15	V
	Voltage detection level Vdet1_6 (1)	At the falling of Vcc	2.85	3.10	3.40	V
	Voltage detection level Vdet1_7 (1)	At the falling of Vcc	3.00	3.25	3.55	V
	Voltage detection level Vdet1_8 (1)	At the falling of Vcc	3.15	3.40	3.70	V
	Voltage detection level Vdet1_9 (1)	At the falling of Vcc	3.30	3.55	3.85	V
	Voltage detection level Vdet1_A (1)	At the falling of Vcc	3.45	3.70	4.00	V
	Voltage detection level Vdet1_B (1)	At the falling of Vcc	3.60	3.85	4.15	V
	Voltage detection level Vdet1_C (1)	At the falling of Vcc	3.75	4.00	4.30	V
	Voltage detection level Vdet1_D (1)	At the falling of Vcc	3.90	4.15	4.45	V
	Voltage detection level Vdet1_E (1)	At the falling of Vcc	4.05	4.30	4.60	V
	Voltage detection level Vdet1_F (1)	At the falling of Vcc	4.20	4.45	4.75	V
—	Hysteresis width at the rising of Vcc in voltage detection 1 circuit	Vdet1_0 to Vdet1_5 selected	—	0.07	—	V
		Vdet1_6 to Vdet1_F selected	—	0.10	—	V
—	Voltage detection 1 circuit response time (2)	At the falling of Vcc from 5 V to (Vdet1_0 – 0.1) V	—	60	150	µs
—	Voltage detection circuit self power consumption	VCA26 = 1, Vcc = 5.0 V	—	1.7	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (3)		—	—	100	µs

Notes:
1. Select the voltage detection level with bits VD1S0 to VD1S3 in the VD1LS register.
2. Time until the voltage monitor 1 interrupt request is generated after the voltage passes V_{det1}.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

5.4 DC Characteristics

Table 5.17 DC Characteristics (1) [4.0 V ≤ Vcc ≤ 5.5 V]
(Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output “H” voltage	Port P10, P11 (1)	V_{CC} = 5V	I_{OH} = –20 mA	V_{CC} – 2.0	—	V_{CC}	V
		Other pins	V_{CC} = 5V	I_{OH} = –5 mA	V_{CC} – 2.0	—	V_{CC}	V
		XOUT	V_{CC} = 5V	I_{OH} = –200 µA	1.0	—	—	V
V_{OL}	Output “L” voltage	Port P10, P11 (1)	V_{CC} = 5V	I_{OL} = 20 mA	—	—	2.0	V
		Other pins	V_{CC} = 5V	I_{OL} = 5 mA	—	—	2.0	V
		XOUT	V_{CC} = 5V	I_{OL} = 200 µA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$, $\overline{INT1}$, $\overline{INT2}$, $\overline{INT3}$, $\overline{INT4}$, $\overline{INT5}$, $\overline{INT6}$, $\overline{INT7}$, $\overline{KI0}$, $\overline{KI1}$, $\overline{KI2}$, $\overline{KI3}$, KI4, KI5, KI6, KI7, TRAIO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, TRGCLKA, TRGCLKB, TRGIOA, TRGIOB, $\overline{ADTRG}$, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO			0.05	0.5	—	V
		$\overline{RESET}$, $\overline{WKUP0}$			0.1	1.0	—	V
I_{IH}	Input “H” current		VI = 5.0 V, V_{CC} = 5.0 V		—	—	5.0	µA
I_{IL}	Input “L” current		VI = 0 V, V_{CC} = 5.0 V		—	—	–5.0	µA
R_{PULLUP}	Pull-up resistance		VI = 0 V, V_{CC} = 5.0 V		25	50	100	kΩ
R_{fXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN			—	14	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Note:
1. This applies when the drive capacity of the output transistor is set to High by registers P10DRR and P11DRR. When the drive capacity is set to Low, the value of any other pin applies.

Table 5.25 External Clock Input (XIN, XCIN)
(Vcc = 1.8 to 5.5 V, Vss = 0 V, and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Standard						Unit
		Vcc = 2.2V, Topr = 25°C		Vcc = 3V, Topr = 25°C		Vcc = 5V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	200	—	50	—	50	—	ns
$t_{WH(XIN)}$	XIN input “H” width	90	—	24	—	24	—	ns
$t_{WL(XIN)}$	XIN input “L” width	90	—	24	—	24	—	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	—	14	—	14	—	µs
$t_{WH(XCIN)}$	XCIN input “H” width	7	—	7	—	7	—	µs
$t_{WL(XCIN)}$	XCIN input “L” width	7	—	7	—	7	—	µs

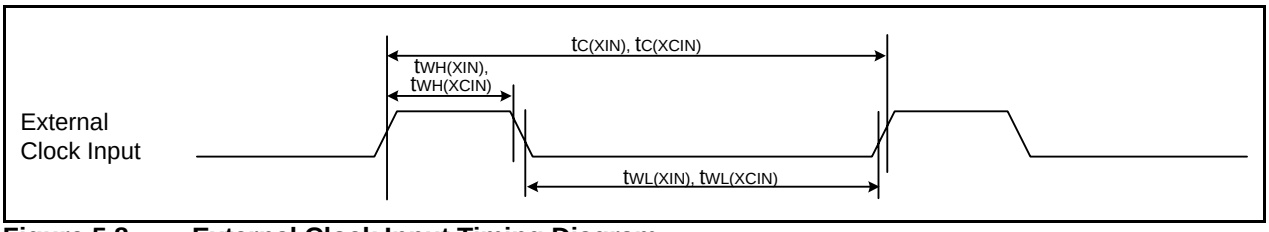


Figure 5.8 External Clock Input Timing Diagram

Table 5.26 Timing Requirements of TRAIO
(Vcc = 1.8 to 5.5 V, Vss = 0 V and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Standard						Unit
		Vcc = 2.2V, Topr = 25°C		Vcc = 3V, Topr = 25°C		Vcc = 5V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	500	—	300	—	100	—	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	200	—	120	—	40	—	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	200	—	120	—	40	—	ns

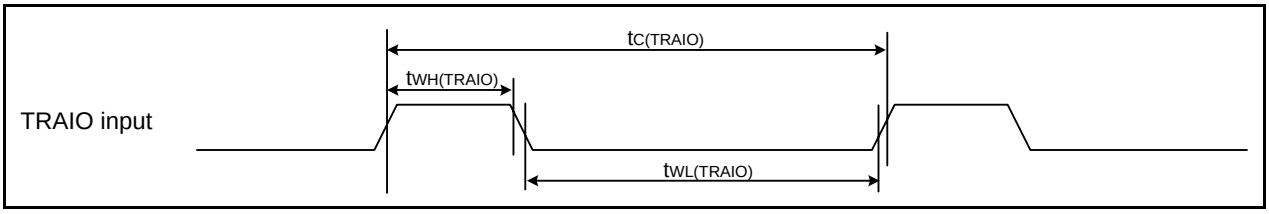
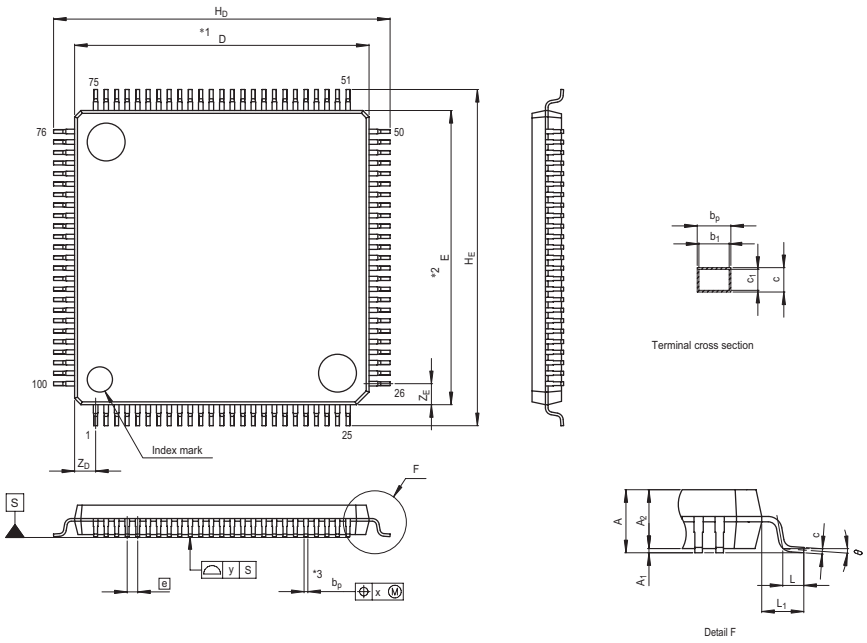


Figure 5.9 Input Timing of TRAIO

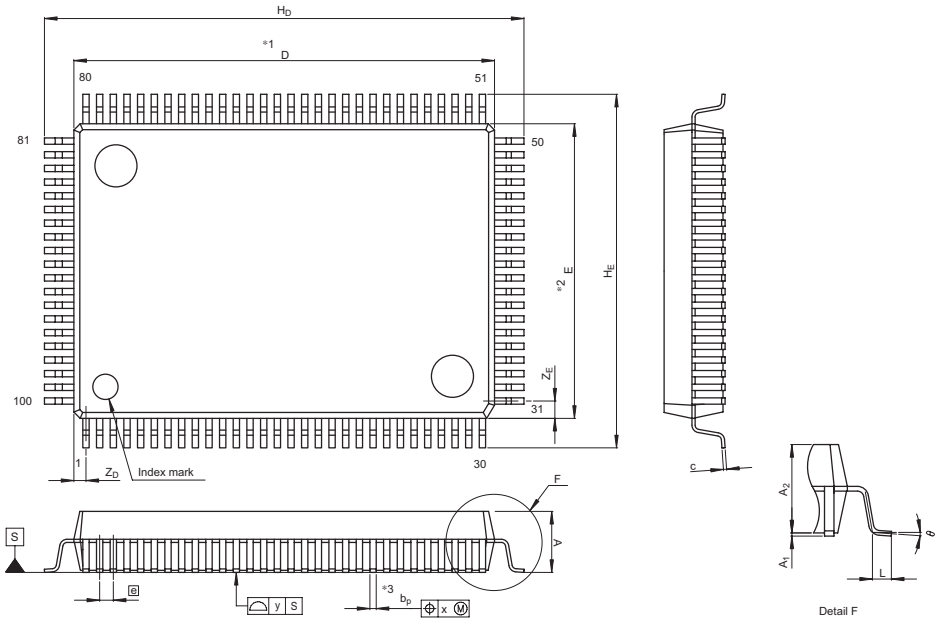
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP100-14x14-0.50	PLQP0100KB-A	100P6Q-A / FP-100U / FP-100UV	0.6g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.35	0.5	0.65
L_1	—	1.0	—

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-QFP100-14x20-0.65	PRQP0100JD-B	100P6F-A	1.8g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	19.8	20.0	20.2
E	13.8	14.0	14.2
A_2	—	2.8	—
H_D	22.5	22.8	23.1
H_E	16.5	16.8	17.1
A	—	—	3.05
A_1	0	0.1	0.2
b_p	0.25	0.3	0.4
c	0.13	0.15	0.2
θ	0°	—	10°
e	—	0.65	—
x	—	—	0.13
y	—	—	0.10
Z_D	—	0.575	—
Z_E	—	0.825	—
L	0.4	0.6	0.8

REVISION HISTORY	R8C/L35C Group, R8C/L36C Group, R8C/L38C Group, R8C/L3AC Group Datasheet

Rev.	Date	Description	
		Page	Summary
0.10	Oct 30, 2009	—	First Edition issued
0.20	Apr 15, 2011	6	Table 1.6 Function deleted, Current consumption revised
		7	1.2 “of R8C/Lx Series” → “for Each Group”
		7 to 10	Tables 1.7 to 1.10 revised
		24	Table 1.15 “Voltage detection circuit” deleted
		29	4. Special Function Registers (SFRs) “The description offered in this chapter is based on the R8C/L3AC Group.” added
		45 to 68	5. Electrical Characteristics added
1.00	Jun 25, 2010	—	“Preliminary” and “Under development” deleted
		1	1.1 revised
		7 to 10	Tables 1.7 to 1.10 revised
		45	Tables 5.1 Note 2 added
		55	Table 5.15 Note 3 added
		69 to 72	Package Dimensions revised
1.01	Apr 15, 2011	2	Table 1.1 revised
		3	Table 1.2 Note 2, Table 1.3 Note 1 revised
		6	Table 1.6 “Flash Memory” revised
		11 to 14	Figure 1.5 to Figure 1.8 revised
		20 to 22	Table 1.11 to Table 1.13 “Voltage Detection Circuit” deleted
		23, 24	Table 1.14 and Table 1.15 title “for R8C/L3AC Group” added
		28	3. “The internal ROM ... with address 0FFFFh.” deleted
		38 to 40	Table 4.10 to Table 4.12 “0248h to 026Fh”, “02A8h to 02BFh”, “02C0h to 02CFh” revised
		48	Table 5.3 “t_{CONV}”, “t_{SAMP}” revised
		57, 59, 61	Table 5.18, Table 5.20, Table 5.22 “High-Speed” → “High-Speed (fOCO-F)”

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Renesas Electronics America Inc.
2880 Scott Boulevard Santa Clara, CA 95050-2554, U.S.A.
Tel: +1-408-588-6000, Fax: +1-408-588-6130

Renesas Electronics Canada Limited
1101 Nicholson Road, Newmarket, Ontario L3Y 9C3, Canada
Tel: +1-905-898-5441, Fax: +1-905-898-3220

Renesas Electronics Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K
Tel: +44-1628-585-100, Fax: +44-1628-585-900

Renesas Electronics Europe GmbH
Arcadiastrasse 10, 40472 Düsseldorf, Germany
Tel: +49-211-65030, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.
7th Floor, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100083, P.R.China
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.
Unit 204, 205, AZIA Center, No.1233 Lujiazui Ring Rd., Pudong District, Shanghai 200120, China
Tel: +86-21-5877-1818, Fax: +86-21-6887-7858 / -7898

Renesas Electronics Hong Kong Limited
Unit 1601-1613, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong
Tel: +852-2886-9318, Fax: +852 2886-9022/9044

Renesas Electronics Taiwan Co., Ltd.
7F, No. 363 Fu Shing North Road Taipei, Taiwan
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

Renesas Electronics Singapore Pte. Ltd.
1 harbourFront Avenue, #06-10, keppel Bay Tower, Singapore 098632
Tel: +65-6213-0200, Fax: +65-6278-8001

Renesas Electronics Malaysia Sdn.Bhd.
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

Renesas Electronics Korea Co., Ltd.
11F., Samik Lavied' or Bldg., 720-2 Yeoksam-Dong, Kangnam-Ku, Seoul 135-080, Korea
Tel: +82-2-558-3737, Fax: +82-2-558-5141

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